




---

## PRODUCT AND PROCESS CHANGE NOTIFICATION

Generic Copy

**This notice is NXP Confidential Proprietary and is only intended for the customer listed on this notification.**

---

**ISSUE DATE:** 04-Feb-2016  
**NOTIFICATION:** 17080  
**TITLE:** MC33931VW / MC33932VW Copper Wire Qualification (HSOP, SM8)  
**EFFECTIVE DATE:** 04-May-2016

### DEVICE(S)

MPN
MC33931VW
MC33932VW
MC33932VWR2

---

**This notice is NXP Confidential Proprietary and is only intended for the customer listed on this notification.**

### AFFECTED CHANGE CATEGORIES

- BILL OF MATERIAL CHANGE (SAME ASSEMBLY SITE)

### DESCRIPTION OF CHANGE

NXP Semiconductors announces the addition of Copper (Cu) wire as a wire bond material along with Sumitomo G700HC mold compound for the MC33931VW and MC33932VW HSOP44 package devices associated with this notification. These products are now qualified for assembly at ASE Korea (ASEKR) assembly site, Korea. These products were previously assembled with Gold (Au) wire and EME6600HR mold compound at ASE Korea (ASEKR) assembly site, Korea.

Samples available for KC33932VW/R2, KC33931VW/R2

### REASON FOR CHANGE

The transfer from Gold to Copper wire and EME6600HR to G700HC mold compound are required to mitigate against raw material cost increases and for supply assurance.

**ANTICIPATED IMPACT OF PRODUCT CHANGE(FORM, FIT, FUNCTION, OR RELIABILITY)**

No change to form, fit or function. Reliability is equivalent or improved.

---

According to JEDEC Standard JESD46, lack of acknowledgement of this PCN within 30 days will be considered acceptance of change. To request further data or inquire about the notification, please enter a [Support Case](#). **Be aware that after you select this link to enter your request, you must choose the topic "Product Change Notification" once on the Salesforce page.**

For sample inquiries - please go to [www.nxp.com](http://www.nxp.com)

---

**QUAL DATA AVAILABILITY DATE:** 17-Dec-2015

**QUALIFICATION STATUS:** COMPLETED

**QUALIFICATION PLAN:**

See attached.

**RELIABILITY DATA SUMMARY:**

See attached.

**ELECTRICAL CHARACTERISTIC SUMMARY:**

No change to Electrical Distributions.

---

**CHANGED PART IDENTIFICATION:**

There is no change to orderable part number. The tracecode marking on the device includes assembly site and datecode. NXP will have traceability by assembly site and datecode.

**SAMPLE AVAILABILITY DATE:** 21-Dec-2015

---

**ATTACHMENT(S):**

External attachment(s) FOR this notification can be viewed AT:

[17080\\_MC33931VW\\_MC33932VW\\_Copper\\_Wire\\_Qualification\\_Results.pdf](#)

[17080\\_MC33932VW\\_Copper\\_Wire\\_Electrical\\_Distribution.pdf](#)

[17080\\_MC33931VW\\_MC33932VW\\_Copper\\_Wire\\_Delta-Qualification-Matrix-ZVEI.pdf](#)

[17080\\_MC33931VW\\_MC33932VW\\_Copper\\_Wire\\_C\\_of\\_DC\\_Comparison.pdf](#)

---